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(54) Title: LARGE FORMAT DIE BOND PLATFORM FOR MICROLED PANEL

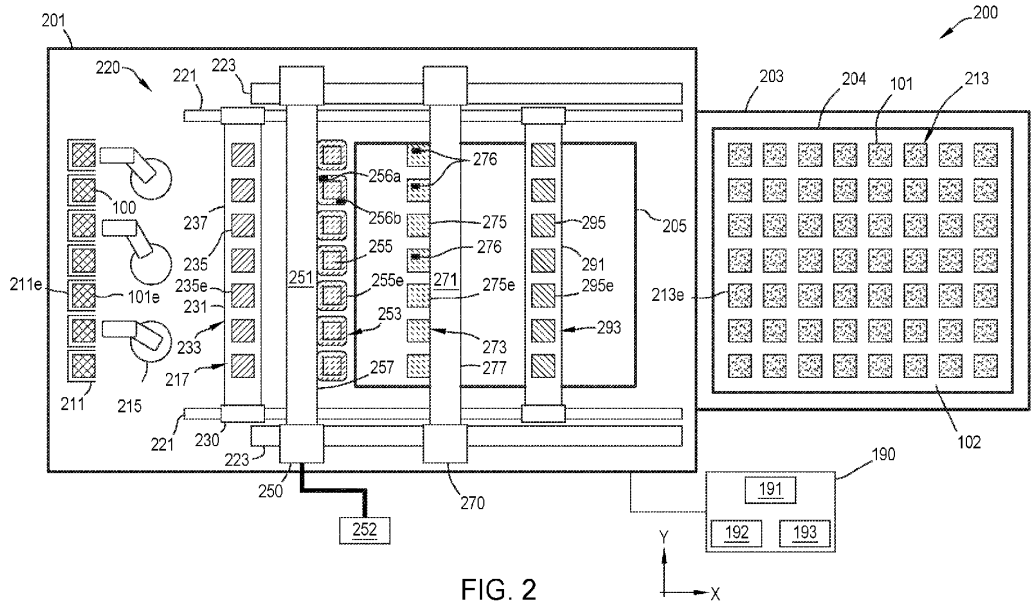


FIG. 2

(57) Abstract: Embodiments of the present disclosure generally relate to die bonding and methods of die bonding LEDs. The method includes disposing a bond head gantry over a first array of dies. The bond head gantry includes an array of bond head modules that corresponds to a respective die of the array of dies. The method also includes retaining the first array of dies with the array of bond head modules, translating, the first array of dies on to an array of elements of the backplane, aligning an array of thermal head modules over the array of bond head modules, the first array of dies, and the array of element, and applying thermal energy with the array of thermal head modules to the first array of dies through the array of bond head modules to bond the first array of dies to the array of elements to form a bonded first array.

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[Continued on next page]

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